

Crystal oscillator



SMD CMOS Output 3.2x2.5x1.0 3N Series

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SPECIFICATION

SJK PN: SJK-3N02500M3C0433E1

深圳市晶科鑫实业有限公司

SHENZHEN CRYSTAL TECHNOLOGY INDUSTRIAL CO., LTD.

SMD CMOS Output 3.2x2.5x1.0 3N Series

FEATURE

- Ultra Small SMD seam sealed clock crystal oscillator units.
- For applications in WLAN, Bluetooth, DSC, DSL and other IT product.
- Tri-state function available.
- RoHS Compliant / Pb Free.

ELECTRICAL SPECIFICATIONS (电气参数)

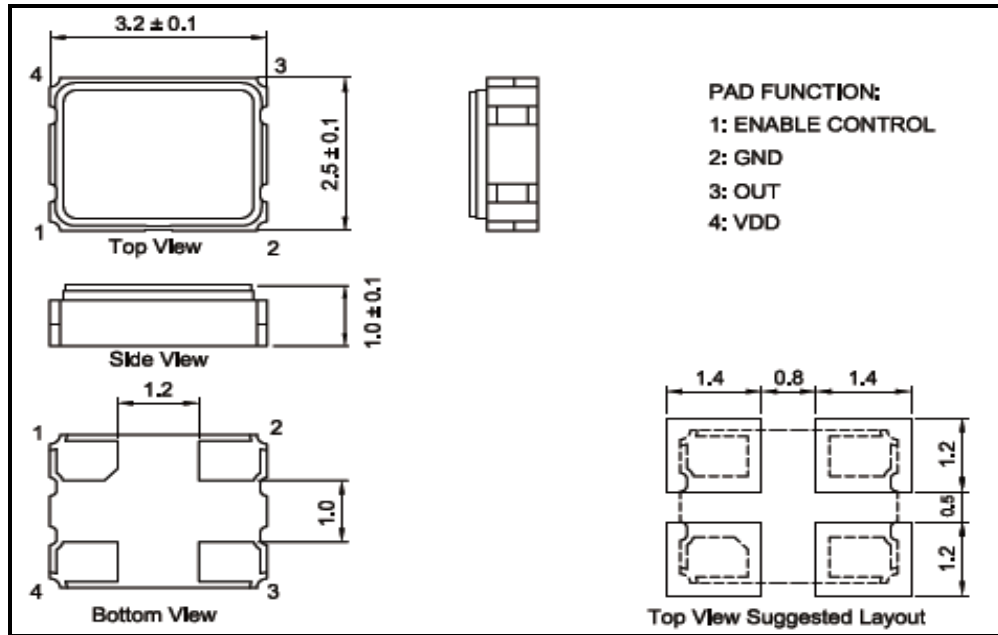
Parmeters	Condition\Model	3N
Fan Out Type		CMOS
Supply Voltage		3.3V±10%
Frequency		25.000MHZ
Operating Temperature		-40~+85℃
Current		15mA max
Frequency Stability	All Conditions	±50ppm
Output Voltage	Vol(max)	10%VDD Min
	VoH(min)	90%VDD Max
Rise/Fall Time	AT 0.1Vdd~0.9Vdd	8ns max
Load Capacitance		15pF
Duty Cycle		50±10%
Storge Temperature		-55~+125℃
Start-upTime	Load RANGE	5ms max(15PF)
Aging		±3ppm(1 st ,year at 25 °C)
Tri-State	Output Active	2.31V Min Pin 1 Tri-state
	Output in High-Impedance state	0.99V Max
PAD Connection	PIN#1 Tri-State/NC	PIN#3 OUT
	PIN#2 GND	PIN#4 Vdd

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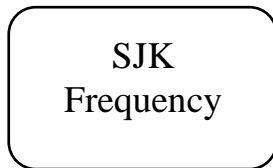


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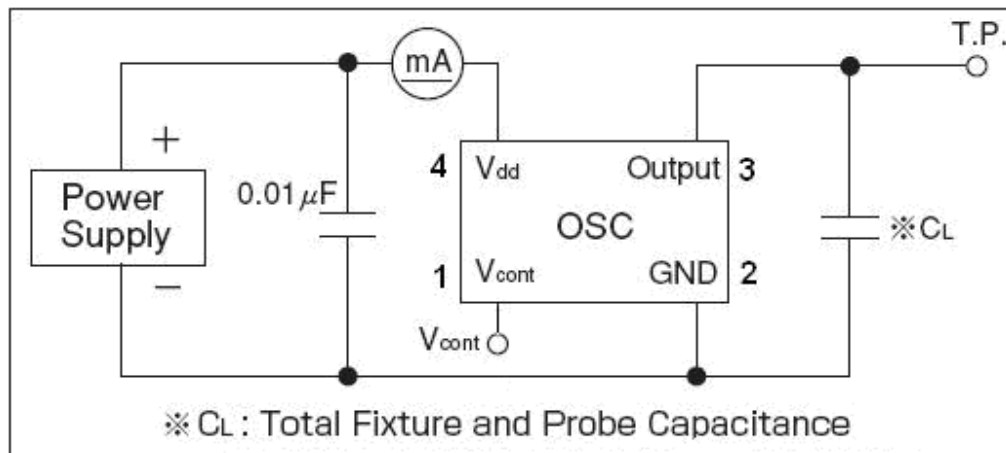
Dimension (尺寸) (Unit: mm)



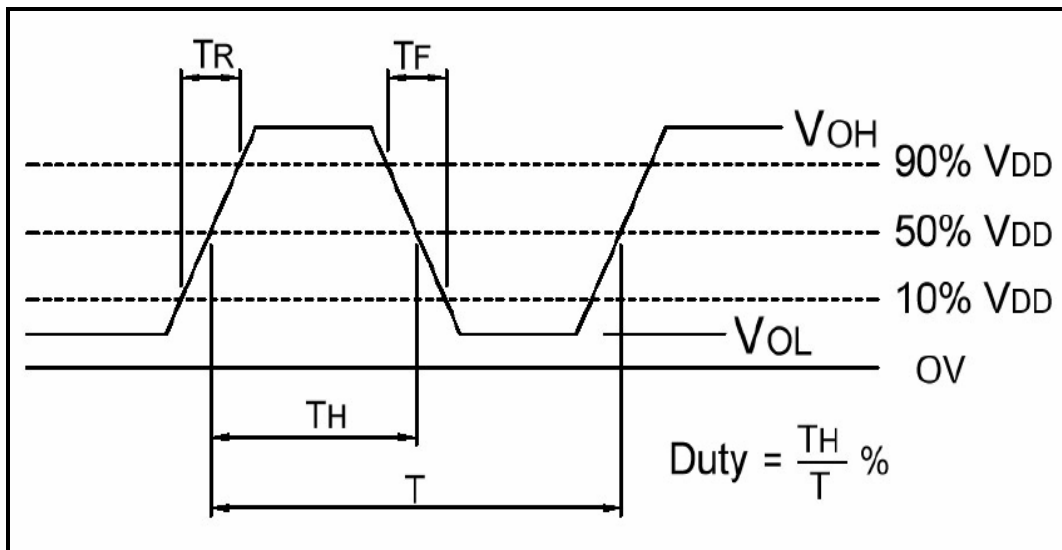
MARK (印字)



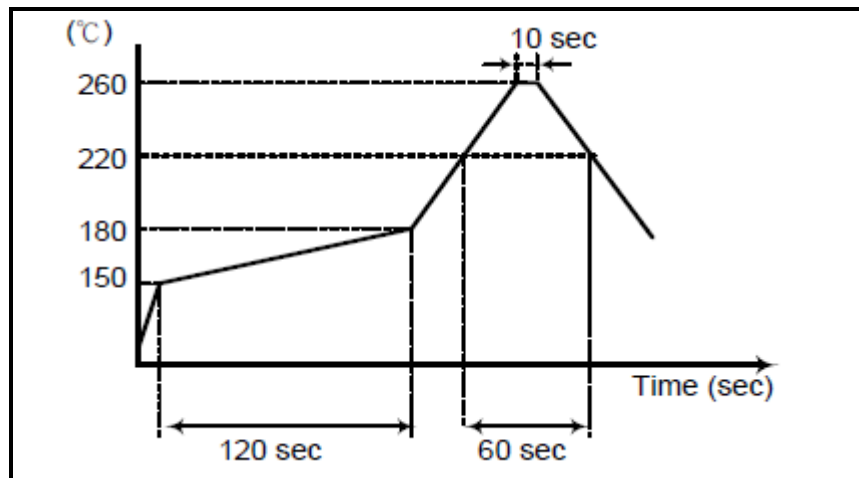
MEASUREMENT CIRCUIT (电路)



WAVEFORM CONDITIONS (波形)



REFLOW CONDITION (回流焊)



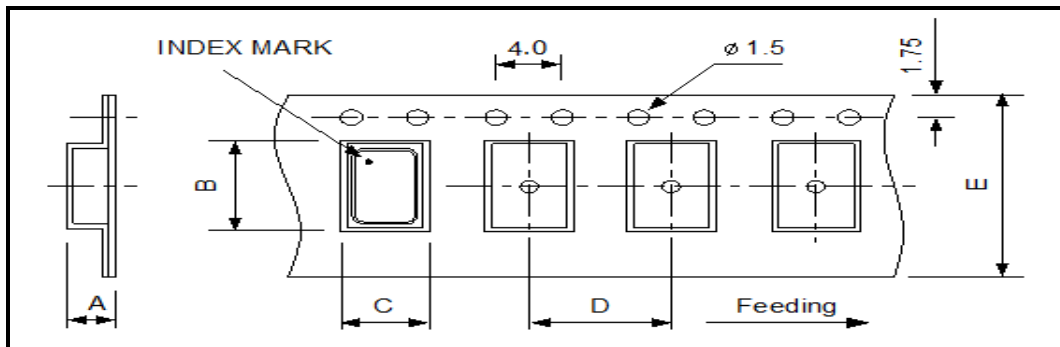
The reflow temperature profile may vary depending on the product model, specifications and frequency range. Refer to the individual product specifications for details

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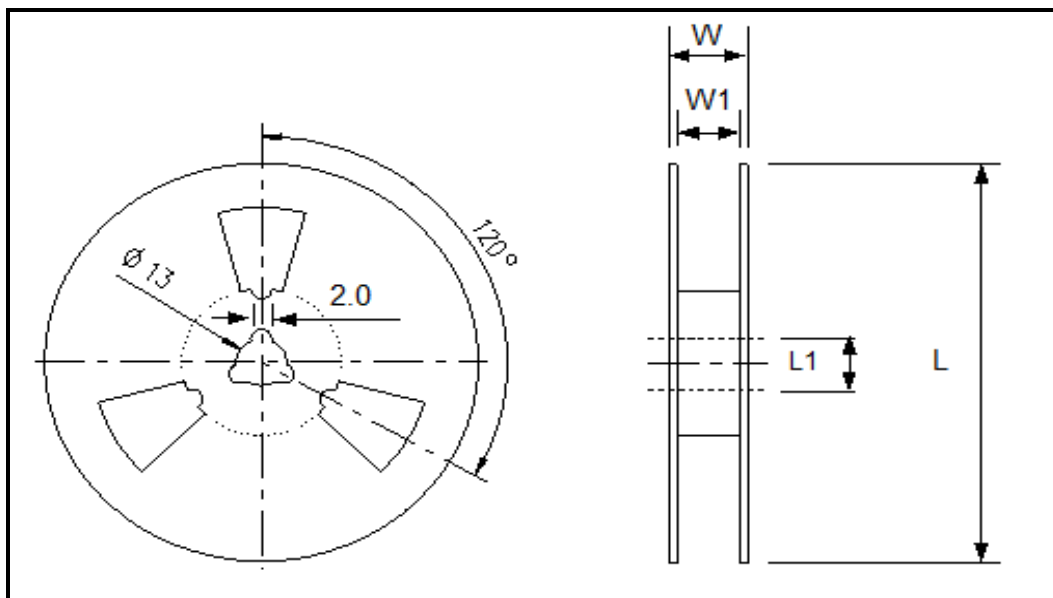


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CARRIER TYPE (載帶)



REEL(卷盘)



DIMENSIONS		A	B	C	D	E	L	L1	W	W1	pcs / Reel
	7050	2.15	7.9	5.4	8	16	180	13	21.5	17.5	1K
	6035	1.4	6.4	3.9	8	12	180	13	15.4	13	1K
	5032	1.46	5.5	3.6	8	12	180	13	15.4	13	1K
	3225	1.4	3.4	2.7	4	8	180	13	11.5	8	3K
	2520	1.15	2.8	2.25	4	8	180	13	10.5	8	3K
	2016	0.95	2.25	2.25	4	8	180	13	10.5	9	3K
	1612	0.8	2.0	1.85	4	8	180	13	10.5	9	3K

RELIABILITY TEST SPECIFICATIONS (可靠性测试标准)

Test item	Equipment	Condition	Specification
1.SOLDERABILITY TEST	SJK-REL001、RC-328A	1.Solderability:235±5℃, 5±0.5S 2.Heat resistance:260±5℃,10±1S restoration of 1 hour	MIL-STD-883E Method 2003.7
2. HERMETICITY TEST	HELIOT-306S	FC-84 FLUOROCARBON,BUBBLE MACHINE	MIL-STD-883E Method 1014.10
3. VIBRATION TEST	HG-V4、S&A 250B	Enable Crystal(10g) from 10-55-10Hz,X、 Y、Z horizontal,1 Minute vibration/time, 1time/ 2 hours.	MIL-STD-883E Method 2007.3
4. MECHANICAL SHOCK	HPC-200、S&A 250B	Enable Crystal 50G(490m/s ²) time=11 ms speed=3.4 m/s half sine wave oscillation	JIS C6701
5. DROP TEST	HARD BOARD.S&A250B	75CM HIGH,3 TIMES ON HARD BOARD	MIL-STD-202F Method 213B
6. HIGH&LOW TEMP STORAGE TEST(Static test)	H-PTH-80CK & HM101- 3ABN, S&A 350B/250B	High temperature: 125℃±2℃,1000hr; Low temperature:-40℃±3℃,1000hrs	MIL-STD883C, METHOD 1011.8
7. TEMP &HUM CYCLING TEST	H-PTH-80CK CHAMBE , S&A 350B/250B	Temperature:-10 ℃ ±2 ℃ ~ 65 ℃ ±2℃,Humidity:93±3%,1 cycle need 24 hrs. 5cycles.	MIL-STD-883E Method 1005.8
8. HIGH TEM. & HUM. STORAGE TEST	H-PTH-80CK CHAMBE , S&A350B/250B	Temperature:40 ℃ ±2 , Humidity:85+3,- 2%,Store 96 hrs	JIS C6701
9.AGING TEST	H-PTH-80CK CHAMBE , S&A350B/250	Temperature: 85℃±2, 1000hrs	JIS C5023